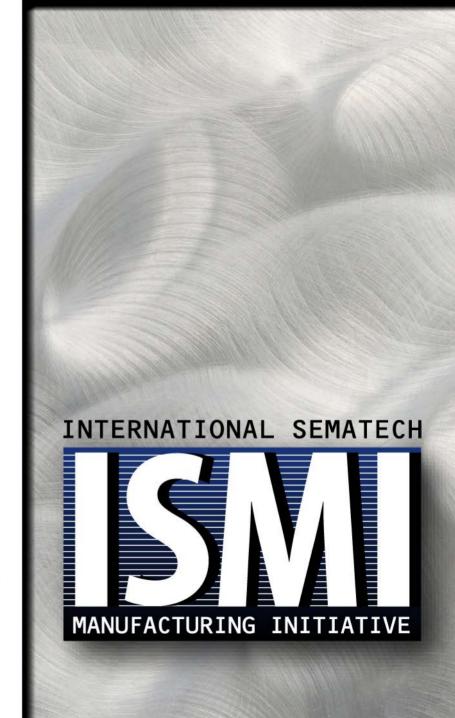
Advancing Factory-Wide Data Quality for APC Applications

Harvey Wohlwend - ISMI Gino Crispieri - ISMI Ya-Shian Li - NIST

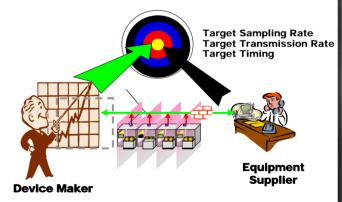
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Outline

- Data Quality Overview
 - Background
 - Industry Experiences
 - IC Maker Consensus
 - Guiding Principles
- Time Synchronization and time-stamping
 - Guidelines
 - Timing Matrix
 - Standards Ballots
 - Key Features
- Data Quality Key Messages
- References



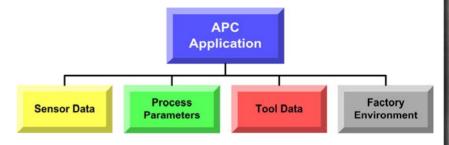


Data Quality Background

- As the industry moves toward automated decisionmaking, the data each tool generates is critical to improving productivity
- Today, the quality of equipment data is poor; it must be dramatically improved if applications are to effectively apply collected data
- APC needs high quality data for accurate decision-making



Industry Data Quality Needs



APC Challenges:

Precision Time Stamping to Merge Various Data Streams

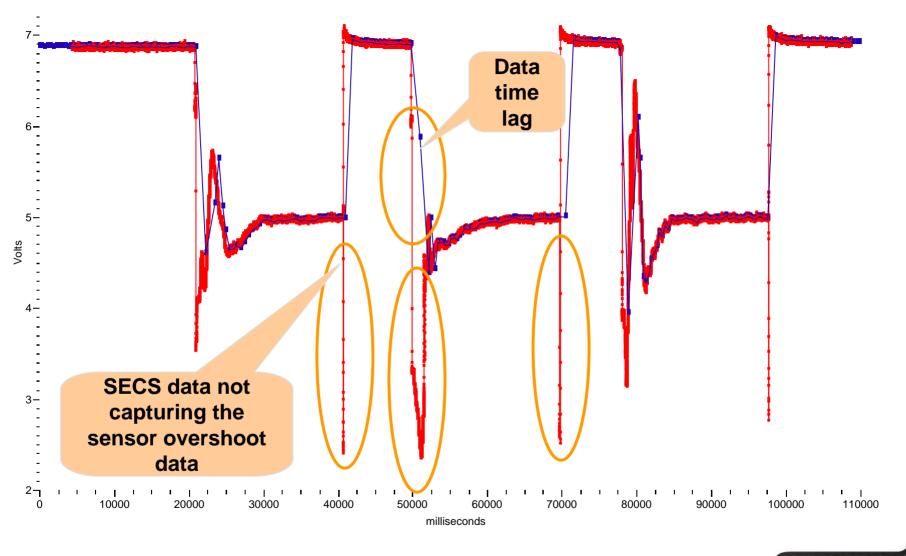
- Unsynchronized sensor/tool data available
- Bandwidths/polling rates vary greatly
- Difficult to synchronize data streams

APC Application Needs:

- Current FDC requirements (10 ms to 1 ms time-stamp precision)
- Support data sampling rates up to 10,000 Hz (< 1 ms precision)
- Equipment/metrology data should synchronize to wafer or lots
- Improve multivariate, advanced correlation and analysis
- Virtual Metrology support
- Expose new cause-effect relationships



Sensor vs. SECS Data Comparison

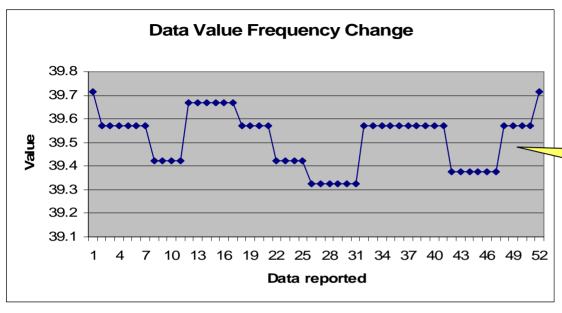


Sensor Impedance

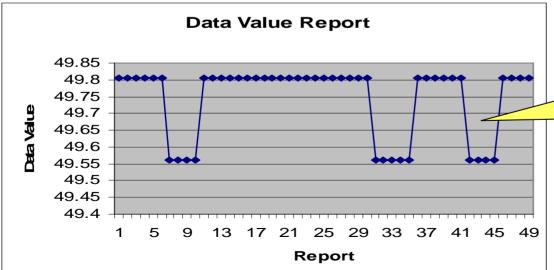
SECS Impedance



Interface A Data Freshness



Running DCP at 100ms shows the values change every 400ms to 750ms



Another problem encountered with a parameter is its resolution. Is a change of 0.2% of full scale acceptable when you may need 0.01% resolution?



IC Maker Consensus Experiences

Issues Experienced

- Equipment interface has software defects
- Documentation does not match software
- Reports send wrong format of data
- Equipment performance affected by data collection
 - Resulting in lost data
- Short data collection period with a high rate can take tool down
 - Resulting in product loss
- Missing data, including context data
- Reporting not current data
- Data report and event latency
- Inaccurate error reporting
- Unclear level of data collection limits, without affecting process
 - Not clear what the equipment is capable off
- Context data missing, e.g., linking data with a wafer
- Non-existent time synchronization
 - Data reports cannot be used to correlate events, alarms, or process issues
- Inconsistent point of timestamping and non-existent time synchronization

Time Synchronization + Time Stamping -> Data Quality



Equipment Data Quality Principles

- Data must be provided with sufficient accuracy, resolution, and sampling frequency to allow high fidelity extraction of relevant data features for process/equipment characterization, fault detection, failure diagnosis, and process control
- Event data and context information must be complete, consistent, and correct as well as reflect the actual time and conditions pertaining to the occurrence of the indicated event
- Timely transfer of data is necessary to achieve fault interdiction
- A time synchronization solution is the initial focus



Time Synchronization Working Group

Mission

Require accurate equipment and factory clock synchronization for future implementations, while maintaining compatibility with legacy systems

Goals

- Factory time source
- Factory clock synchronization precision
- Embedded clocks within equipment need to be synchronized with factory clock
- Factory applications timing requirements
- Common time-stamp format/basis
- Consistent point of time-stamping
- Synchronization traceability/quality for verification
- Facilitate data merging and analysis

SEMI Time Synchronization Working Group

- IC makers and equipment/software suppliers
- To participate, contact: Harvey.Wohlwend@ismi.sematech.org



Time Synchronization Approach

- 1. Leverage definitions from standard sources, e.g., NIST, ISO, IEEE
- 2. Publish Time Synchronization Guidelines
 - Characterized processes for timing accuracy and precision requirements
 - ismi.sematech.org/docubase/abstracts/4781aeng.htm
- 3. Specifications in new standard
 - Submitting to SEMI for balloting



- 4. Update existing standards to support time synchronization/time-stamping
 - E5, E30, E40, E54, E116, E127, E133, E134
 - Backward compatibility is an <u>absolute</u> requirement



Guideline Objective

To complement the proposed new time synchronization standard and provide guidance in establishing a factory time synchronization architecture for realizing effective data collection and time-stamping

Goals:

- Facilitate the establishment of effective factory time synchronization architecture
- Ensure synchronization quality
- Provide recommendations and methods for meeting the new SEMI Time Synchronization standard requirements
- Guidance on data time-stamping for ensuring data quality
- Guidance on current and upcoming time synchronization accuracy requirements





Time Synchronization and Time-Stamping Guidelines Overview

Time Synchronization Architecture

- UTC time scale
- Reference time source and traceability
- NTP strata and modes
- Fault tolerance

Time Synchronization Quality

- Clock quality
- Synchronization frequency
- Security
- Monitoring

Accuracy and Precision Requirements

- Current and upcoming requirements based on working group discussions
- General agreement is about 1 ms accuracy for e-Manufacturing applications

Effective Time-Stamping

- Timestamp format and time base
- Point of time-stamping





Implementer Roles & Responsibility

Chapter	Guideline Items	Device Maker	Equipment Supplier	Software Suppliers
6.1	Time Synchronization Guidelines			
6.1	UTC Time Scale			
6.2	Factory Time Servers			
6.3	Time Synchronization Traceability			
6.4	Fault Tolerance			
6.5	Time Source			
6.6	Synchronization Protocol			
6.7	Client Configuration			
6.8	Synchronization Architecture			
6.8.1	Stratum Levels			
6.9	Clock Quality			
6.10	Clock Resolution			
6.11	Synchronization Frequency			
6.12	Network Jitter			
6.13	Synchronization Performance			
6.14	Security Practices			
6.15	Data Time Stamping Guidelines			
6.15.1	Time Base			
6.15.2	Time Stamp Format			
6.15.3	Time Stamping Data			
6.15.4	Time Stamping Resolution			



Time Synchronization Requirements

Equipment clocks must:

- Synchronize to factory time servers via NTP
- Communicate UTC date/time information based on ISO 8601
- Converge to single time base, e.g., NTP
- Provide synchronization quality parameters as defined in SEMI ballot 4291
- Provide synchronization error messages as defined in SEMI ballot 4291
- Provide configurable NTP synchronization parameters

Factory Time Synchronization Recommendations:

- Fault-tolerant synchronization architecture
- Improve clock quality to minimize synchronization resources
- Ensure sufficient synchronization frequency
- Adhere to factory network security measures
- Minimize jitter in network and applications during synchronization
- Ensure sufficient clock resolution for the most stringent requirements
- Monitor synchronization quality





Time-Stamping Requirements

Data time-stamping must:

- Adhere to the format defined in the SEMI 4291 ballot
- Reflect only the resolution of the clock

Data time-stamping recommendations:

- Reflect the time when the data was measured
- Mitigate latencies between data generation and time-stamping
 - Record types of latencies (network, application, etc.)
 - Calculate total latency
 - Provide an estimated timestamp based on calculations

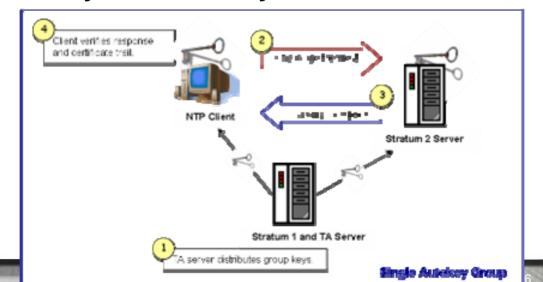


4.0

Time Synchronization Architecture

Achieving 1 ms time synchronization accuracy requires carefully architected time synchronization system

- Clients should be able to exchange the local time to the server whenever processing and network bandwidth are available
- Minimizing network jitter (variability in network delay) improves synchronization quality
- A stable, high resolution clock improves time stamping quality while relieving the time synchronization frequency and network bandwidth
- Adhere to security precautions to avoid accidental or malicious interference with system clock synchronization

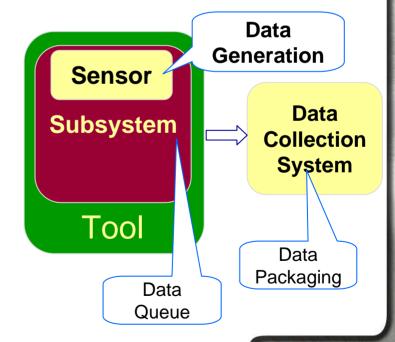




Time Stamping Data

Time stamps coupled with a piece of data shall reflect the time the data was measured, generated as closely as possible to provide a sufficient level of data quality.

 Include accuracy information on the time stamp including estimated clock deviation from UTC and estimated time stamping latency from when the event occurred to when it was actually time-stamped





Application Timing Requirements On-tool Examples

Application	Description/Needs	Absolute Accuracy	Relative Accuracy	Minimum Data Sampling Interval	Precision Required
Intra-tool Sensor Integration	Connect sensors to embedded tool control system for use in real-time control and/or communication to external applications.	5 sec	5 ms	5 ms	1 ms
End-Point Detection	Analyze key equipment/process parameters to detect the end of a recipe step.	5 sec	10 ms	10 ms	1 ms
In-Situ FDC	Need to correlate sensor data, tool data, and other process data to a specific wafer/lot for multivariate analysis.	5 sec	5 ms	5 ms	1 ms
Integrated Metrology (IM)	Standard calls for synchronized clocks to accurately time stamp metrology data.	5 sec	100 ms	100 ms	1 ms



Time Synchronization Ballot (4291)

Specifications in new standard

- Equipment and factory applications shall support synchronization using NTP
- Time-stamp reporting format (ISO 8601)
 - Format to be used by other standards
- Defines a clock object
 - To readily obtain time information from equipment
 - Method to query date/time
 - Accuracy/precision of internal clock
 - Time synchronization status



Existing Standards Update

Define immediate needs and specific tasks for updating and developing SEMI standards to facilitate rapid deployment of factory and equipment clock synchronization.

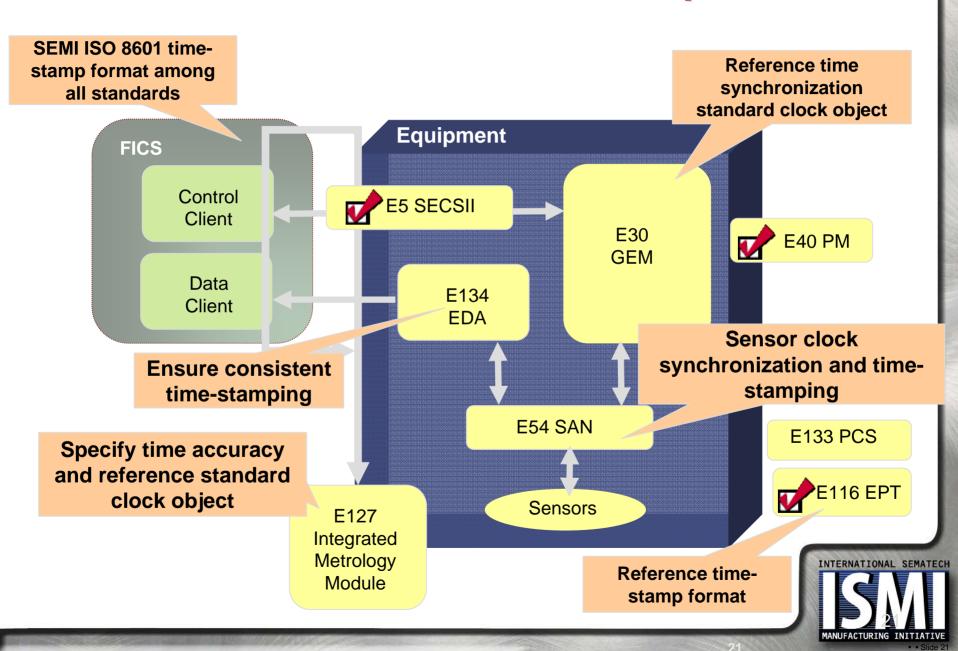
Goals

- Establish factory clock synchronization
- Facilitate data merging
 - Common time-stamp format
 - Consistent point of time-stamping
 - Time-stamp traceability/quality
- Leverage new SEMI Time Synchronization ballot
- Maintain compatibility with legacy systems





SEMI Standards: Planned Updates



Time Synchronization Summary

- Data from sensors and tools cannot be readily merged today to meet factory application needs
 - Unreliable time-stamps prevent advanced analysis capabilities
 - Clocks within the tools should readily synchronize
 - All tool and tool components' clocks should support synchronization
- Synchronization solutions exist
 - The factory provides accurate timing
 - Time servers and time sources inside the factory should propagate timing information to all equipment and equipment modules using mainstream synchronization protocols
- Standards/guidelines being developed to
 - Improve synchronization communication of equipment clocks
 - Provide consistent time-stamping
 - Verify clock synchronization/time-stamping quality
- Time synchronization is an initial step to addressing the overall data quality issue

Data Quality Key Messages

- Data <u>producers</u> are the equipment suppliers; they are the only ones that can improve data quality.
- Data <u>consumers</u> are IC makers, who are at the mercy of the <u>producers</u>; the <u>quality</u> of the <u>decisions</u> made is wholly dependent on the <u>quality</u> of the <u>data</u>.

Garbage in, garbage out

- Semiconductor equipment generates data critical to improving equipment and factory productivity.
- Data must be provided with sufficient accuracy, resolution, and sampling frequency for process/ equipment characterization, fault detection, failure diagnosis, and process development/control.

How does your organization measure data quality? What are the costs associated with the lack of data quality?



Time Synchronization References

ISMI Reports

- Factory and Equipment Clock Synchronization and Time Stamping Guidelines ismi.sematech.org/docubase/abstracts/4781aeng.htm
- Using Network Time Protocol (NTP): Introduction and Recommended Practices ismi.sematech.org/docubase/abstracts/4736aeng.htm
- Semiconductor Factory and Equipment Clock Synchronization for e-Manufacturing ismi.sematech.org/docubase/abstracts/4557aeng.htm

ISO 8601:2004

• Internet standard for date/time format: www.w3.org/TR/NOTE-datetime.html

NTP

- www.ntp.org
- Latest official NTP RFC 1305: www.ietf.org/rfc/rfc1305.txt
- NTP version 4 Working Draft: www.ietf.org/internet-drafts/draft-ietf-ntp-ntpv4-proto-02.txt

IEEE 1588

• ieee1588.nist.gov



